TECHNOLOGY DEVELOPMENT ENGINEER

Responsibilities:

- To establish new design for lead frame and laminated substrate packages solution based on customer & market trend / requirement.
- To develop new design rules for lead frame and substrate based on assembly processes capability & international standard
- Act as project manager for any new development activities including plan, execution, timeline, cost, investment, customer communication etc.

Requirements:

- Degree in Engineering or Science discipline.
- Knowledge in semiconductor assembly processes & packaging will be added advantage.
- Understanding in engineering drawing, e.g. CAD etc.
- Independent and self-motivated with good communication and interpersonal skills.
- Able to work with all levels of employees and customers.

Interested applicants are invited to write-in / email with a comprehensive resume to:
HUMAN RESOURCE DEPARTMENT
UNISEM (M) BHD
No 1, Persiaran Pulai Jaya 9,
Kawasan Perindustrian Pulai Jaya,
31300 Ipoh Perak.
Telephone No. : +605-3572800
Email : recruiting@unisemgroup.com